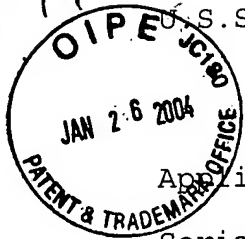


1756



U.S.S.N. 10/051,906

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Chao-Yuan Su et al.

Group Art Unit: 1756

Serial No.: 10/051,906

Examiner: J. Ruggles

Filed: 01/15/2002

In Response to Office Action

Dated: 10/22/2003

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JAN 26 2004

TC 1700

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JAN 30 2004

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For: A METHOD OF FORMING A SOLDER BALL USING A
THERMALLY STABLE RESINOUS PROTECTIVE LAYER

Attorney Docket No.: 67,200-630

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Va 22313-1450

Date: Jan. 21, 2004

Kathy Dixon

RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, Va 22313-1450

Dear Sir:

In response to an Office Action mailed 10/22/2003 please consider the following remarks. The Commissioner is hereby authorized to charge Deposit Account No. 50-0484 any fee due as a result of this amendment.